

# **TV East/West Correction Circuit for Square Tubes**

Technology: Bipolar

#### **Features**

- Low dissipation
- Square generator for parabolic current specially designed for square C.R.T. correction
- External keystone adjustment (symmetry of the parabola)
- Input for dynamic field correction (beam current change)
- Static picture width adjustment
- Pulse-width modulator
- Final stage D-class with energy redelivery
- Parasitic parabola suppression, during flyback time of the vertical sawtooth

Case: 8 pin dual inline plastic

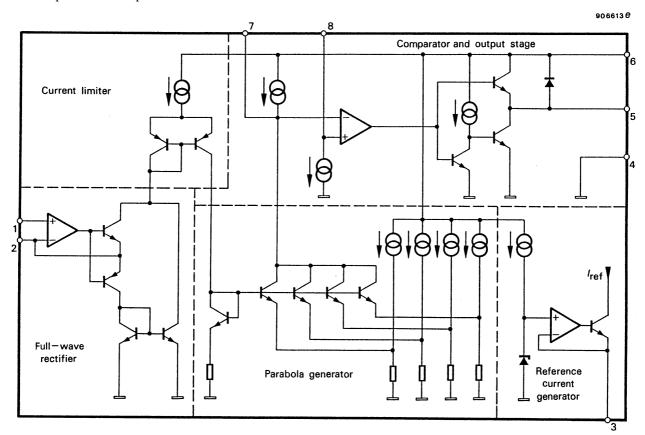


Figure 1. Block diagram

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## **Absolute Maximum Ratings**

Parame	Symbol	Value	Unit	
Supply voltage	Pin 6	$V_{S}$	35	V
Supply current	Pin 6	$I_{S}$	500	mA
Power dissipation $T_{case} = 50^{\circ}$	°C	P <sub>tot</sub>	500	mW
Storage temperature range		T <sub>stg</sub>	-25 to 150	°C
Junction temperature		Ti	-25 to 150	°C

### **Electrical Characteristics**

 $V_S = 26$  V,  $T_{amb} = 25$ °C, Test circuits 1 to 5

Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	Pin 6	$V_{S}$	17	24	30	V
Supply current	Test circuit 1 Pin 6	I <sub>S</sub>		4.5	7	mA
Reference voltage	Test circuit 1 Pin 3	V <sub>ref</sub>	7.6	8.0	8.8	V
Voltage at Pin 7 *	Test circuit figure 2, Pin 7 $I_{fr} = 0 \; \mu A \\ I_{fr} = 30 \; \mu A$	V <sub>7A</sub> V <sub>7C</sub>	15.3	16.0 15.0	16.7	V
Parabola coefficient	$K_1 = rac{V_{7A} - V_{7B}}{V_{7A} - V_{7C}}$ $K_2 = rac{V_{7A} - V_{7C}}{V_{7A} - V_{7D}}$			26 70		%
Difference, figure 2	$V_{DE7} = V_{7E} - V_{7F}$		-40	0	40	mV
Current source	Test circuit 3 Pin 8	I <sub>8</sub>		100		μA
Saturation voltage	$I_5 = 400 \text{ mA},$ Pin 5 Test circuit 4 $I_5 = -100 \text{ mA},$ Pin 5 Test circuit 5	V <sub>satL</sub>		1 0.8	2	V V
Forward voltage	$I_5 = 400 \text{ mA}, \qquad \text{Pin 5}$ Test circuit 5	VsatH		1.2	1.7	V

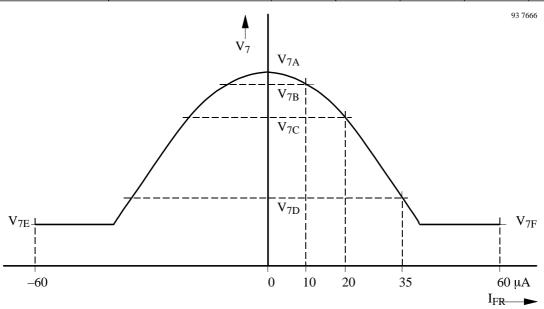


Figure 2. Parabola coefficients

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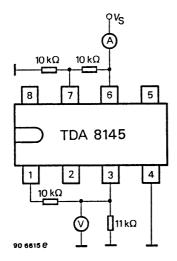


Figure 3. Test circuit 1

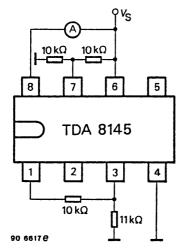


Figure 5. Test circuit 3

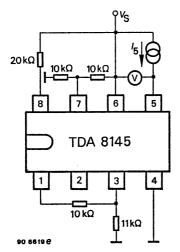


Figure 7. Test circuit 5

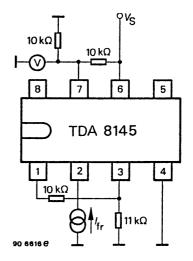


Figure 4. Test circuit 2

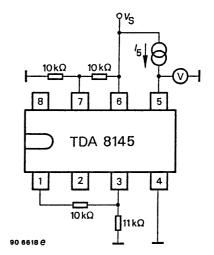


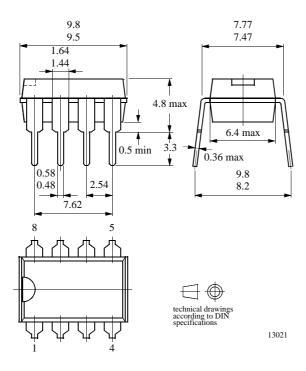
Figure 6. Test circuit 4

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### **Dimensions in mm**

Package DIP8
Dimensions in mm



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#### **Ozone Depleting Substances Policy Statement**

It is the policy of **TEMIC Semiconductor GmbH** to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**TEMIC Semiconductor GmbH** has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

**TEMIC Semiconductor GmbH** can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

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